

WEST**End of Result Set**

Generate Collection

Print

L1: Entry 2 of 2

File: DWPI

Jul 19, 2001

DERWENT-ACC-NO: 2002-133789

DERWENT-WEEK: 200218

COPYRIGHT 2003 DERWENT INFORMATION LTD

TITLE: Printed wiring board for electronic device, has conductive plug which is connected to electrical circuit comprised by interconnection groove and through hole fitted with hardened electroconductive paste

PATENT-ASSIGNEE:

ASSIGNEE

SONY CORP

CODE

SONY

PRIORITY-DATA: 2000JP-0006687 (January 14, 2000)

PATENT-FAMILY:

PUB-NO

PUB-DATE

LANGUAGE

PAGES

MAIN-IPC

JP 2001196703 A

July 19, 2001

010

H05K001/02

APPLICATION-DATA:

PUB-NO

APPL-DATE

APPL-NO

DESCRIPTOR

JP2001196703A

January 14, 2000

2000JP-0006687

INT-CL (IPC): H05 K 1/02; H05 K 1/03; H05 K 3/12; H05 K 3/40; H05 K 3/46

ABSTRACTED-PUB-NO: JP2001196703A

BASIC-ABSTRACT:

NOVELTY - An interconnection groove (14) formed on an electrically insulated substrate (12) made up of thermoplastic resin, is filled with hardened electroconductive paste and a through hole (18) penetrating the interconnection groove is filled with hardened electroconductive paste for comprising an electrical circuit (16). A conductor plug (20) penetrating the substrate is filled with electrical circuit.

DETAILED DESCRIPTION - An INDEPENDENT CLAIM is also included for printed circuit board production method.

USE - Double sided and multilayer printed wiring board for mounting electronic components in electrical and electronic devices.

ADVANTAGE - The electroconductive paste has melting point below the curing temperature of adhesive layer such that the joining of the printed circuit board, formation interconnection groove and through hole can be performed simultaneously and hence, reliable circuit board with dimensional stability and connection stability is obtained. Contact area of conductor plug and conductor circuit embedded in the through hole is increased, thereby improving electrical connection reliability.

DESCRIPTION OF DRAWING(S) - The figure shows the sectional view of printed wiring board. (Drawing includes non-English language text).

WEST



Generate Collection

Print

L1: Entry 1 of 2

File: JPAB

Jul 19, 2001

PUB-NO: JP02001196703A

DOCUMENT-IDENTIFIER: JP 2001196703 A

TITLE: PRINTED WIRING BOARD AND MANUFACTURING METHOD FOR THE SAME

PUBN-DATE: July 19, 2001

INVENTOR-INFORMATION:

NAME

COUNTRY

SAKURAI, TOSHIHIRO

IZUMI, MASAHIRO

OGAWA, MINORU

ASSIGNEE-INFORMATION:

NAME

COUNTRY

SONY CORP

APPL-NO: JP2000006687

APPL-DATE: January 14, 2000

INT-CL (IPC): H05 K 1/02; H05 K 1/03; H05 K 3/12; H05 K 3/40; H05 K 3/46

ABSTRACT:

PROBLEM TO BE SOLVED: To provide a printed wiring board of new structure comprising a substrate of thermoplastic resin and a conductor circuit of a conductive paste printed on the substrate.

SOLUTION: A printed wiring board 10 comprises an electrical insulating substrate 12 of a thermoplastic resin, a conductor circuit 16 wherein a wiring groove 14 formed in one surface of the substrate is filled with a conductive paste for solidification, and a conductor plug 20, where a through-hole 18 penetrating the substrate 12 through the wiring groove 14 is filled with the conductive paste for solidification, which connects to the conductor circuit 16, while penetrating the substrate 12. In the manufacturing method for the printed wiring board, at least one through-hole is formed in one surface of the substrate by heat-press molding with a stamper or injection molding method, which penetrates the wiring groove or the substrate through it. Then the through-hole and wiring group are filled with a conductive paste for solidification and then connected to the conductor circuit, constituting a conductor plug which penetrates the substrate as well. Another substrate is bonded to the printed wiring board, and a wiring groove and through-hole are formed with a stamper so that a both-sided substrate or a multilayered substrate comprising 3 layers or more is formed.

COPYRIGHT: (C)2001,JPO

Electrically insulated substrate 12

Interconnection groove 14

Electrical circuit 16

Through hole 18

Conductor plug 20

CHOSEN-DRAWING: Dwg.1/6

TITLE-TERMS: PRINT WIRE BOARD ELECTRONIC DEVICE CONDUCTING PLUG CONNECT ELECTRIC
CIRCUIT COMPRISE INTERCONNECT GROOVE THROUGH HOLE FIT HARDEN ELECTROCONDUCTING PASTE

DERWENT-CLASS: A85 L03 U11 U14 V04

CPI-CODES: A99-A; L03-H04E; L04-C13B;

EPI-CODES: U11-C05G2C; U14-H03B1; U14-H04A3; V04-Q02A; V04-R02; V04-R05A; V04-R05B;
V04-R07L;

SECONDARY-ACC-NO:

CPI Secondary Accession Numbers: C2002-041181

Non-CPI Secondary Accession Numbers: N2002-101197